

DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: ELECTRONIC DEVICE WORKPIECES, METHODS OF SEMICONDUCTOR PROCESSING AND METHODS OF SENSING TEMPERATURE OF AN ELECTRONIC DEVICE WORKPIECE, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

EL979949672**PRIOR FOREIGN APPLICATIONS:**

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

1 Section 1001 of Title 18 of the United States Code and that such willful
2 false statement may jeopardize the validity of the application or any
3 patent issued therefrom.

4 * * * * *

5 Full name of inventor: SALMAN AKRAM

6 Inventor's Signature: Salman Akram

7 Date: 2/25/98

8 Residence: Boise, Idaho

9 Citizenship: Pakistan

10 Post Office Address: 1463 E. Regatta Street, Boise, ID 83706

11 * * * * *

12 Full name of inventor: DAVID R. HEMBREE

13 Inventor's Signature: David R. Hembree

14 Date: 2/25/98

15 Residence: Boise, Idaho

16 Citizenship: U.S.A.

17 Post Office Address: 10855 W. Smoke Ranch Dr., Boise, ID 83709